

Spec. No. : C553QP Issued Date : 2010.10.27 Revised Date : Page No. : 1/12

2A Low Dropout LDO EM5102AQP

General Description

EM5102A is a 2A low dropout linear regulator designed for low dropout and high current applications. This device works with dual supplies, a control input for the control circuitry and a power input as low as 1.2V for providing current to output. It features 2A output current and ultra-low-drop output voltage as well as full protection functions. Vour can be as low as 0.8V.

Features

- •VIN Range 1.2V to 5.5V
- •Vout is Adjustable (0.8V Min)
- •Excellent Line Regulation
- •Excellent Load Regulation

•300mV @ 2A Dropout Voltage
•OTP and OCP Functions
•Very Low On-Resistance
•Enable & Power good Signal

Applications

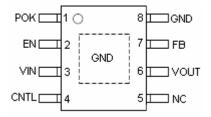
- Notebook & Netbook
- •Graphic Cards & MB
- •Low Voltage Logic Supplies

•Chipset Supplies •Server System •SMPS Post Regulators

Ordering Information

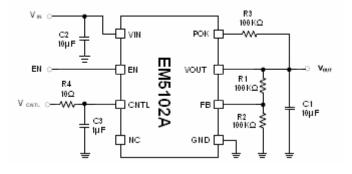
Part Number	Package				
EM5102AQP	PSOP-8				
	(Pb-free lead plating package)				

Pin Configuration





Typical Application Circuit

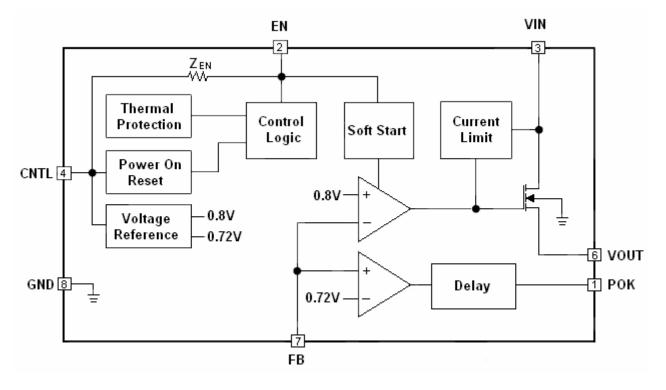


Pin Assignment

Pin Name	Pin No.	Pin Function
РОК	1	Power OK Indication. POK is an open-drain output. An external pull high resistor connected to this pin is required.
EN	2	Enable Input. Pulling the pin below 0.4V turns the regulator off
VIN	3	Input Voltage. This is the drain input to the power device that supplies current to the output pin. VIN cannot be forced higher than VCNTL.
CNTL	4	Supply Input for Control Circuit. CNTL provides supply voltage to the control circuitry and driver for the pass transistor. The driving capability of output current is proportioned to the VCNTL. For the device to regulate, the voltage on this pin must be at least 2.0V greater than the output voltage, and no less than VCNTL_MIN.
NC	5	No Connection inside chip.
VOUT	6	Output Voltage. Vout is power output pin. An internal pull low resistance exists when the device is disabled. Minimum 10μ F low ESR ceramic holding capacitor is required at this pin for stabilizing Vout voltage.
FB	7	Feedback Voltage. FB is the inverting input to the error amplifier. A resistor divider from the output to GND is used to set the regulation voltage as $V_{OUT} = (1 + R1/R2) \times 0.8V$ (V). This pin has high impedance and should be kept from noisy source to guarantee stable operation.
GND	8	Ground.



Function Block Diagram



Absolute Maximum Ratings (Note 1)

•V _{IN} 0.3V to	+7.0V
•VCNTL (Note 1)0.3V to	+7.0V
•Other Pins0.3V to (VCNTL-	+0.3V)
•Package Thermal Resistance, θJA, PSOP-8 (Note 2) 72	5°C/W
•Package Thermal Resistance, θJC, PSOP-8 (Note 2) 1	5°C/W
• Power Dissipation, PD @ TA = 25°C, PSOP-8 (Note 3)	1.9W
•Junction Temperature	150°C
•Lead Temperature (Soldering, 10 sec.)	260°C
•Storage Temperature65°C to) 150°C
•ESD susceptibility (Note4)	
HBM (Human Body Mode) MM (Machine Mode)	2KV
WIWI (MIACHINE WIOGE)	200V

Recommended Operating Conditions (Note5)

Supply Input Voltage, VIN	1.0V to V CNTL
Control Voltage, VCNTL	3.0V to 5.5V
Junction Temperature	-40°C to 125°C
Ambient Temperature	-40°C to 85°C



Electrical Characteristics @ $V_{CNTL}=5V$, TA=25°C, unless otherwise specified

	r	1			n	
Parameter	Symbol	Test Conditions	Min	Тур	Max	Units
Supply Input Section						
Control Input Voltage	VCNTL	Vout= Vref	2.9	-	6	V
POR Threshold	VCNTLRTH		2.5	2.7	2.9	V
POR Hysteresis	VCNTLHYS		0.1	0.2	-	V
Power Input Voltage	Vin	Vout=Vref	1.0	-	VCNTL	V
Control Input Current in	Icntl_sd	VIN=VCNTL=5V, IOUT=0A,VEN=0V	-	10	30	μΑ
Quiescent Current	Iq	Vin=Vcntl=Ven=5V, Iout=0A, Vout=Vref	-	0.3	0.6	mA
Feedback						
Reference Voltage	Vref	Vin=Vcntl=Ven=5V, Iout=0A, Vout=Vref	0.788	0.8	0.812	V
Feedback Input Current	Ifb		-	20	-	nA
V _{IN} Line Regulation	VREF(LINE)	1.2V <vin<5v, vcntl="VEN=5V,<br">Iout=0A, Vout=Vref</vin<5v,>	-	0.01	0.1	%/V
Load Regulation (Note 6)	VREF(LOAD)	0 <iout<2a, vin="Vcntl=Ven=5V,<br">Vout=Vref</iout<2a,>	-	0.1	0.5	%/A
Load Regulation over Temperature	Vref(total)	0 <iout<2a, vin="VCNTL=VEN=5V,<br">Vout=VREF, -40° C<tj<125° by<br="" c="">design</tj<125°></iout<2a,>	-	0.5	3	%
On Resistance	Rds(ON)	Iout=100mA, Vcntl=Ven=5V, Vout=1.6V	-	150	250	mΩ
Dropout Voltage (Note 7)	Vdrop	IOUT=2A, VCNTL=VEN=5V, VOUT=1.6V	-	300	500	mV
Output Voltage	Vout		0.8		VCNTL-2	V
Vout Pull Low Resistance		VIN=VCNTL=5V, VEN=0V	-	70	-	Ω
Enable			1			
Enable High Level	VEN		1.4	-	-	V
Disable Low Level	Vsd		-	-	0.4	V
Enable Source Current	Ien	VCNTL=5V, VEN=0V	-	7	18	μA
Enable Input Impedance	Zen		-	650	-	KΩ
Output Voltage Ramp Up Time			1.5	2.5	4.5	ms
PWROK						
FB Power OK Threshold	VIN-VONTI-VEN-5V JOUT-0		-	90	-	%
Power ()K Hysteresis Vpokhys		Vin=Vcntl=Ven=5V, Iout=0A, Vout=Vref	-	8	-	%
POK Delay Time		From Vout>90% to POK rising	2	4	6	ms
Over Current Protection		· · · · · · · · · · · · · · · · · · ·			•	
OCP Threshold Level	IOCP	VIN=VCNTL=VEN=5V, VOUT=VREF	2.5	2.8	-	А
Output Short Circuit Current	Isc	VIN=VCNTL=VEN=5V, VOUT=0V	1.0	1.6	-	А



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Parameter	Symbol	Test Conditions	Min	Тур	Max	Units			
Thermal Protection									
Thermal Shutdown Temperature	Tsd	Vin=Vcntl=Ven=5V, Iout=0A, Vout=Vref	-	170	-	°C			
Thermal Shutdown Hysteresis	Tsdhys	VIN=VCNTL=VEN=5V, IOUT=0A, Vout=Vref	-	30	-	°C			

Note 1. Stresses listed as the above "Absolute Maximum Ratings" may cause permanent damage to the device. These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability.

Note 2. θJA is measured in the natural convection at TA=25°C on a 4-layers high effective thermal conductivity test board with minimum copper area of JEDEC 51-7 thermal measurement standard. The case point of θJC is on the expose pad for PSOP-8 package.

Note 3. θ JA is 52°C/W for PSOP-8 packages on JEDEC 51-7 (4 layers,2S2P) thermal test board with 50mm² copper area.

Note 4. Devices are ESD sensitive. Handling precaution is recommended.

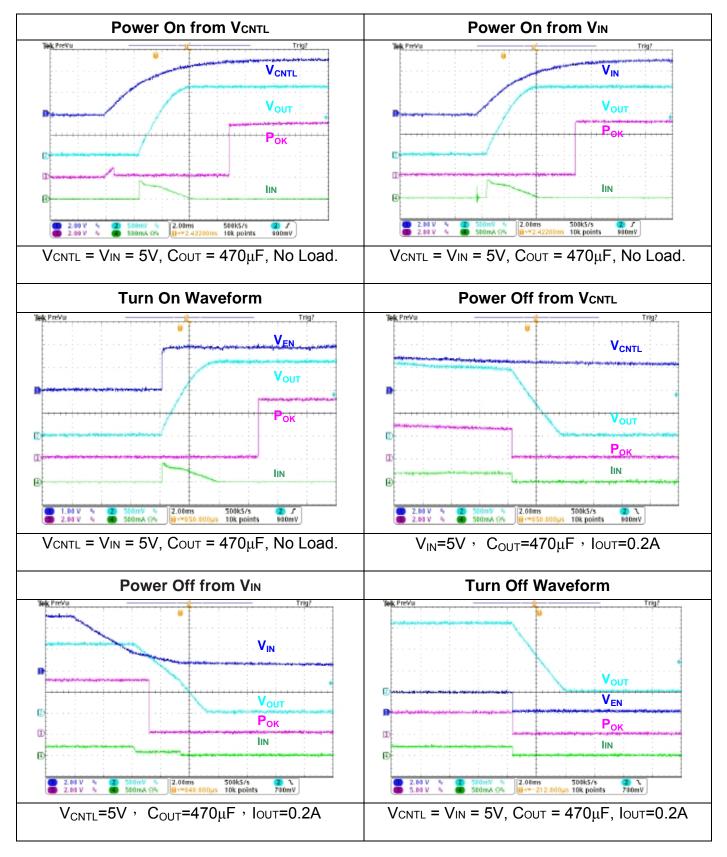
Note 5. The device is not guaranteed to function outside its operating conditions.

Note 6. Load regulation is measured by a current pulse with 50Hz frequency and 10% duty cycle.

Note 7. The dropout voltage is defined as (VIN-VOUT), which is measured when VOUT equal to (VOUT,(NORMAL)-100mV).

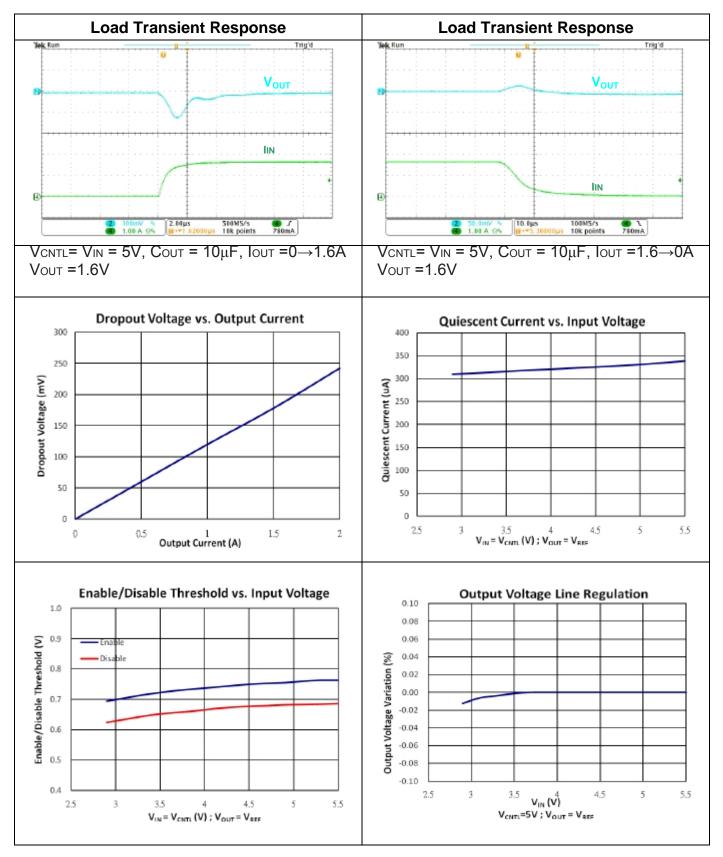


Typical Operating Characteristics



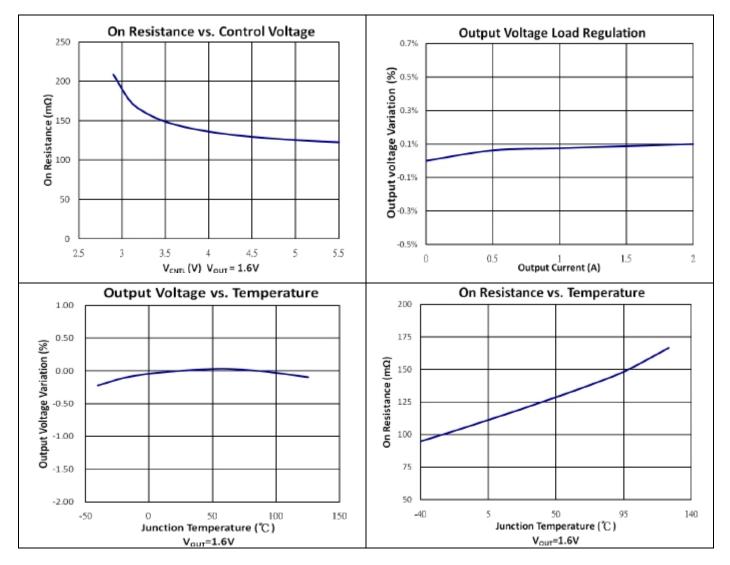


Typical Operating Characteristics(Cont.)





Typical Operating Characteristics(Cont.)



CYStek Product Specification



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Functional Description

Enable Function

EM5102A is enabled if the voltage of the EN pin is greater than 1.4V. If the voltage of the EN pin is less than 0.4V, the IC will be disabled. The quiescent current can be decreased to be less than 10μ A typically.

POR – Power ON Reset

To let EM5102A start to operation, CNTL voltage must be higher than its POR voltage even when EN voltage is pulled higher than enable high voltage. Typical POR voltage is 2.7V.

VOUT Voltage Adjustment

The VOUT voltage of EM5102A can be adjusted by external voltage divider. Refer to typical application circuit, VOUT voltage is calculated by the following equation:

V OUT =
$$(1 + \frac{R_1}{R_2}) \times 0.8V$$

Over Current Limit Function

EM5102A features over current limiting function as well as output short circuit current fold back function. Typically, before the thermal protection is triggered, EM5102A can limit its output current to 2.8A. When output voltage is decreased, the limiting current level also decreases. When VOUT is short to GND, or VOUT voltage is zero, the output current level is limited to 1.6A, typically.

Input and Output Capacitor Selection

For CNTL pin, a 1 μ F ceramic capacitor is enough for bypass the supply of CNTL to GND. For VIN pin, 10 μ F or larger ceramic capacitor is required to provide bypass path in transient current demand. Vout pin is also recommended to have 10 μ F or larger ceramic capacitor to be stable and reduce the Vout voltage dip when fast loading transient is happened. A feed-forward capacitor can be placed between Vout and FB pin to speed up the transient response, optionally.

Power Dissipation

The max power depends on some conditions, including of thermal impedance, PCB layout, airflow, and so on. The max power dissipation can be calculated by the formula as below:

$P_{D(max)} = (T_{J(max)} - T_A) / \theta_{JA}$

 $T_{J(max)}$ is the max junction temperature; θ_{JA} is the thermal impedance from junction to ambient. The thermal impedance θ_{JA} of exposed SOP-8 is package design and PCB design dependent.

The thermal impedance can be reduced by increasing the copper area under the exposed pad of the SOP-8 package. So, to let the copper area as large as possible is helpful for the thermal performance of the exposed SOP-8 package.



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For recommended specification of EM5102A, the max junction temperature is 125 degree C. The θ_{JA} of exposed SOP-8 is 75°C/W on the standard JEDEC 51-7(4 layers, 2S2P, copper 2 oz) thermal test board. The max power dissipation (at 25°C ambient, on the min exposed pad layout) can be calculated as below:

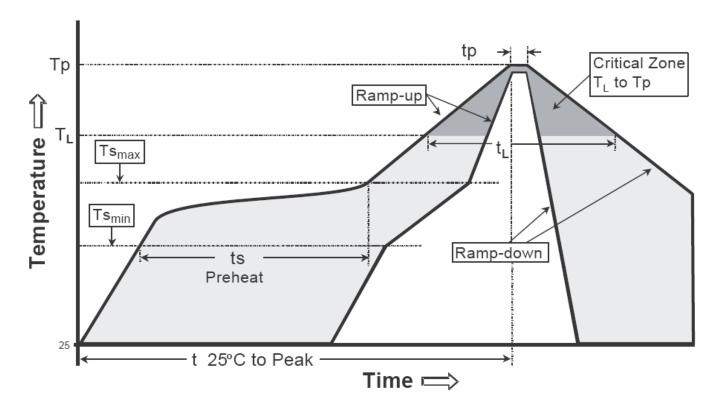
 $P_{D (max at 25^{\circ}C)} = (125^{\circ}C - 25^{\circ}C) / (75^{\circ}C/W) = 1.33W$



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow

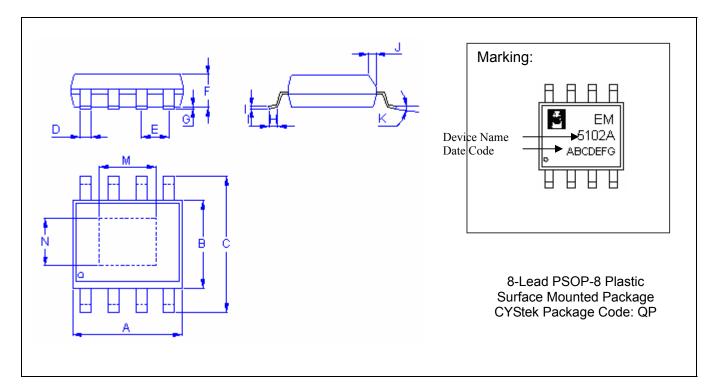


Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly		
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.		
Preheat				
-Temperature Min(Ts min)	100°C	150°C		
-Temperature Max(Ts max)	150°C	200°C		
-Time(ts min to ts max)	60-120 seconds	60-180 seconds		
Time maintained above:				
–Temperature (TL)	183°C	217°C		
– Time (t∟)	60-150 seconds	60-150 seconds		
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C		
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds		
Ramp down rate	6°C/second max.	6°C/second max.		
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.		

Note : All temperatures refer to topside of the package, measured on the package body surface.



PSOP-8 Dimension



*:Typical

. Typical									
DIM	Inches		Millimeters		DIM	Inches		Millimeters	
DIN	Min.	Max.	Min.	Max.	DIN	Min.	Max.	Min.	Max.
А	0.1850	0.2008	4.70	5.10	Н	0.0157	0.0327	0.40	0.83
В	0.1457	0.1614	3.70	4.10		0.0075	0.0102	0.19	0.26
С	0.2283	0.2441	5.80	6.20	J	0.0098	0.0197	0.25	0.50
D	0.0130	0.0200	0.33	0.51	K	0 °	8°	0 °	8 °
E	E 0.05*		1.2	7 *	М	0.0764	0.0980	1.94	2.49
F	0.0472	0.0638	1.20	1.62	Ν	0.0764	0.0980	1.94	2.49
G	0.0032	0.0110	0.08	0.28					

Notes : 1.Controlling dimension : millimeters.

2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material. 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material :

• Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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